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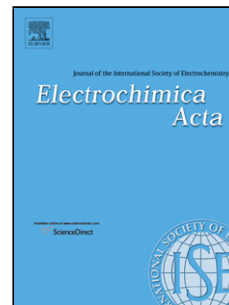
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A facile process combined with inkjet printing, surface modification and electroless deposition to fabricate adhesion-enhanced copper patterns on flexible polymer substrates for functional flexible electronics

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